

SpeedFam IPEC 372M



The IPEC Avanti 372 wafer polisher is a fully automated, precision tool for chemical mechanical planarization (CMP) polishing of semiconductor wafers. It can planarize wafers from 100 mm to 200 mm and is ideally suited for materials polishing applications that require repeatability with operational and processing flexibility. The wafer polisher features automatic wafer handling and is capable of two platen, two-step polishing processing to maximize wafer throughput capability and quality.

The IPEC 372 uses a CMP polishing process to remove virtually any semiconductor material using polishing slurry to planarize the wafers to achieve flatness, uniformity and planarization on patterned/device wafers. The wafer polisher provides: fully automated precision polishing, processing flexibility and repeatable results.

Wafer Sizes: 2 inch, 3 inch, 100 mm, 125 mm, 150 mm and 200 mm

For Novellus (SpeedFam / IPEC)
refurbished CMP equipment:
info@entrepix.com

For Novellus (SpeedFam / IPEC)
CMP spare parts:
parts@entrepix.com

For Novellus (SpeedFam / IPEC)
service or maintenance:
service@entrepix.com

Or Call:
602-426-8677 (Sales)



Our Expertise, Our Services, Your Success

SpeedFam IPEC 372M

Preventative Maintenance Program

Overview

- General Clean and Inspections
- Clean and Lubricate All Rails and Drives
- Baseline Equipment
- Load Calibrations
- Platen Run Out
- Arm Sweet Calibrations
- Carrier Run Out
- Down Force Calibration
- Back Pressure Calibrations
- Pad Conditioner Operations Check
- Unload Calibrations
- Tool-Specific Issues Addressed

Upgrades and Refurbishment

Overview

- Steady Sweep Pad Conditioner
- Platen Lapping
- Gear Box Refurbishment
- Pad Puller
- Monitor Upgrade
- Slurry Injector (Araca)